

# EUROPEAN PATENT OFFICE

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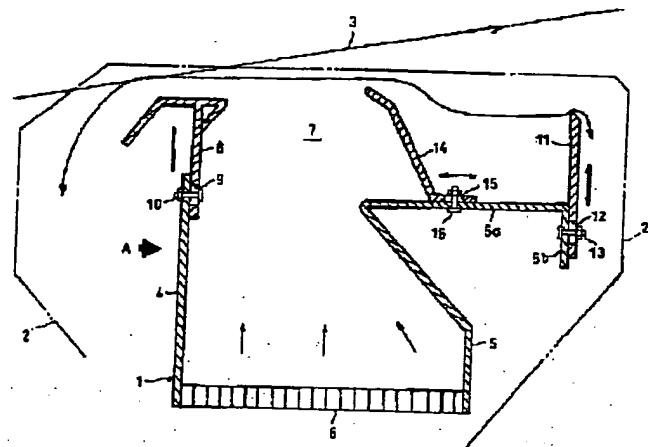
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APPLICANT : KOKI:KK;

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TITLE : SPOUTING SOLDER VESSEL NOZZLE



**ABSTRACT :** PROBLEM TO BE SOLVED: To obtain stable peel back point suitable to kind of a printed board and to improve the soldering efficiency by executing the adjustment of vertical moving of a front part wave-form forming plate, the adjustment of shifting in the front and the back parts of a back part wave-form forming plate and the adjustment of vertical moving of a weir plate in a spouting solder vessel nozzle.

**SOLUTION:** In the spouting solder vessel nozzle, the wave-form forming plate 8 flowing out the solder drawing the arc toward the advancing direction of the printed board 3, is arranged so as to be adjustable to vertically move on the upper part of a front part nozzle constituting part 4 at the front part of the solder spouting nozzle A. The weir plate 11 for adjusting the wave-form is arranged so as to be adjustable to vertically move, while connecting with the upper end of a back part nozzle constituting plate 5 at the back part of the spouting nozzle A or at the back part of a tray constituting plate 5a. The back part wave-form forming plate 14 for keeping higher height than the front part wave-form forming plate 8 and the weir plate 11, is arranged so as to be adjustable to shift to the front and the back parts on the tray constituting plate 5a. The position of separating point of the solid and the flow speed of the solder are controlled in always stable condition by adjusting in the single movement or the whole movement of the front and the back plate wave-form forming plates 8, 14 and the weir plate 11.

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